



DONGGUAN NANJING ELECTRONICS LTD.,
SMC Plastic-Encapsulate Diodes

SS32 THRU SS320 Schottky Rectifier Diodes

Features

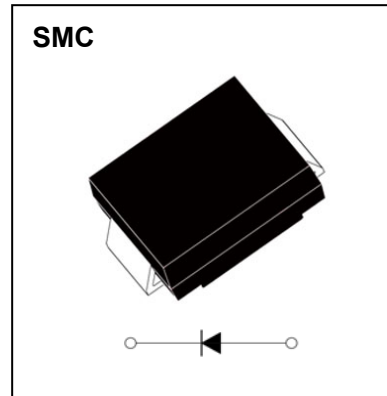
- $I_{F(AV)}$ 3A
- V_{RRM} 20V-200V
- High surge current capability
- Polarity: Color band denotes cathode

Applications

- Rectifier

Marking

- SS3X
- X : From 2 To 20



Limiting Values(Absolute Maximum Rating)

Item	Symbol	Unit	Test Conditions	SS3								
				2	3	4	5	6	8	10	15	20
Repetitive Peak Reverse Voltage	V_{RRM}	V		20	30	40	50	60	80	100	150	200
Maximum RMS Voltage	V_{RMS}	V		14	21	28	35	42	56	70	105	140
Average Forward Current	$I_{F(AV)}$	A	60HZ Half-sine wave, Resistance load, TL(FIG.1)	3.0								
Surge(Non-repetitive)Forward Current	I_{FSM}	A	60Hz Half-sine wave , 1 cycle , $T_a = 25^\circ\text{C}$	100								
Junction Temperature	T_J	$^\circ\text{C}$		-55~+150								
Storage Temperature	T_{STG}	$^\circ\text{C}$		-55 ~ +150								

Electrical Characteristics ($T = 25^\circ\text{C}$ Unless otherwise specified)

Item	Symbol	Unit	Test Condition	SS3							
				2	3	4	5	6	8	10	15
Peak Forward Voltage	V_F	V	$I_F = 3.0\text{A}$	0.55		0.7		0.82		0.90	
Peak Reverse Current	I_{RRM1}	mA	$V_{RM} = V_{RRM}$	$T_a = 25^\circ\text{C}$		0.2		0.1			
	I_{RRM2}			$T_a = 100^\circ\text{C}$		5.0					
Thermal Resistance(Typical)	$R_{\theta J-A}$	$^\circ\text{C/W}$	Between junction and ambient		47 ¹⁾						
	$R_{\theta J-L}$		Between junction and terminal		13 ¹⁾						

Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas

Typical Characteristics

FIG.1: FORWARD CURRENT DERATING CURVE

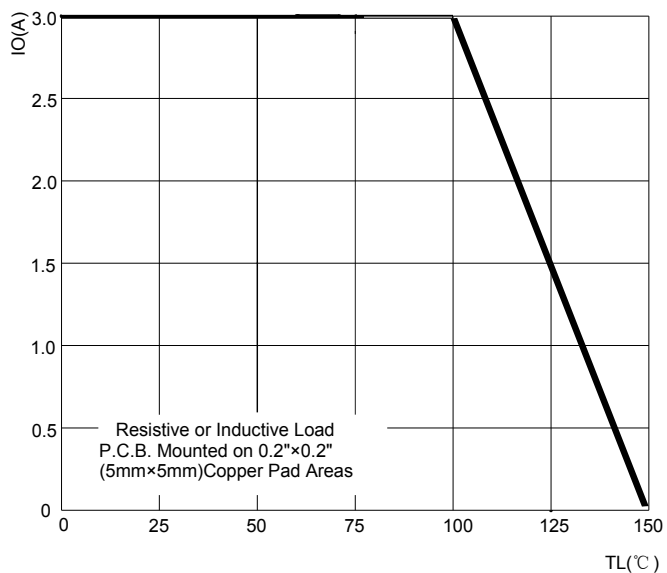


FIG.2: MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

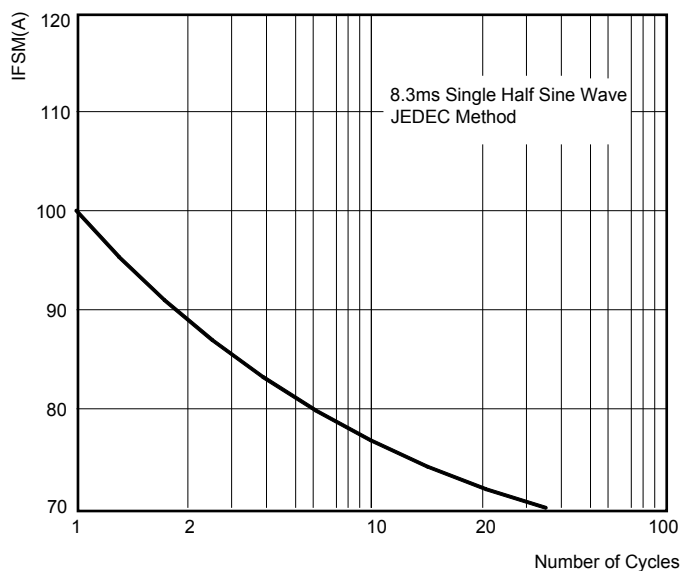


FIG.3: TYPICAL FORWARD CHARACTERISTICS

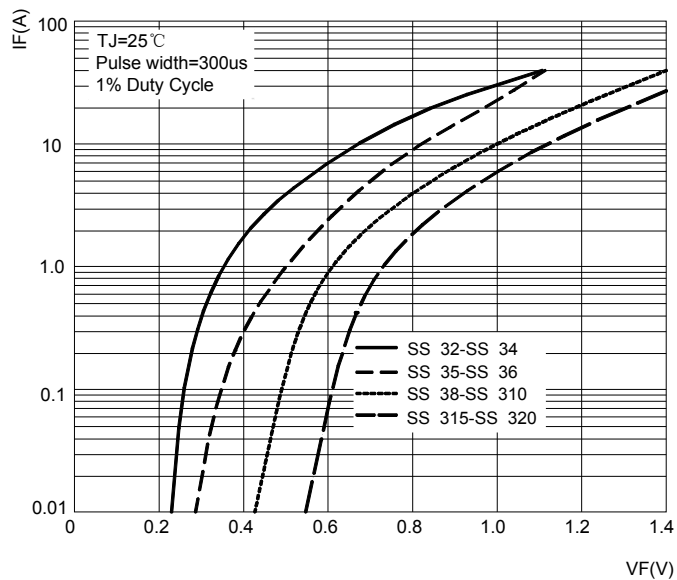
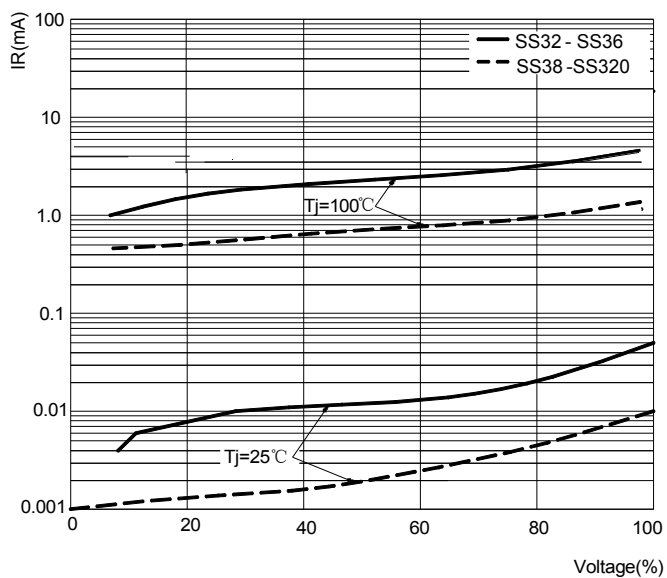
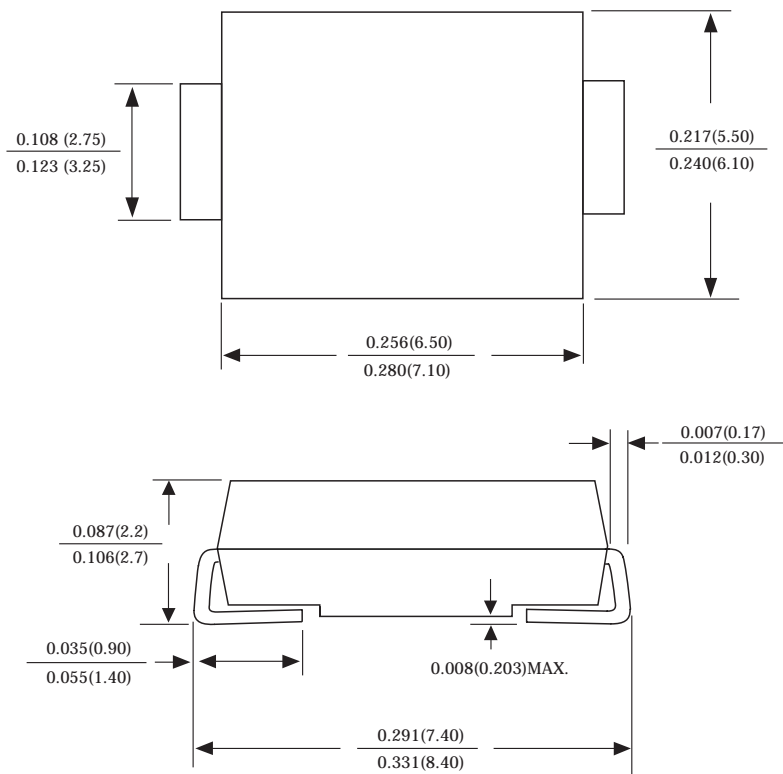


FIG.4: TYPICAL REVERSE CHARACTERISTICS

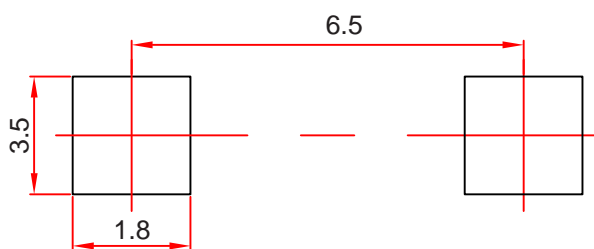


SMC Package Outline Dimensions



Dimensions in inches and (millimeters)

SMC Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.

Reel Taping Specifications For Surface Mount Devices–SMC



FIG: CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL	SMC mm(inch)
Carrier width	A	6.05±0.1(0.238±0.004)
Carrier length	B	8.31±0.1(0.327±0.004)
Carrier depth	C	2.70±0.1(0.106±0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	330±2.0(13±0.079)
Reel inner diameter	D1	75 ±1.0 (2.95 ±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Strocket hole position	E	1.75 ±0.1(0.069±0.004)
Punch hole position	F	7.65±0.05(0.301±0.002)
Punch hole pitch	P	8.0±0.1(0.315±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Total tape thickness	T	0.3 ± 0.1 (0.012±0.004)
Tape width	W	16.0±0.2(0.630±0.008)
Reel width	W1	24.0±2.0(0.945±0.079)

NOTE: Devices are packed in accordance with EIA standard RS-481-A and specification given above.